

3EC-M1S-VLP

- ・ 无载体箔之 $7\mu\text{m}$ 薄铜箔, 具高抗张力特性。
Thin foil ($7\mu\text{m}$), high tensile strenght, supply without carrier foil.
- ・ 极低粗糙度电解铜箔, 适用于极细线路蚀刻之减成法制程。
Low profile copper foil, suitable for fine etching in the subtractive process.

用途/Application

- ・ 软性电路板
/Flexible Print Board

构成/Composition



生产地点/Production Site

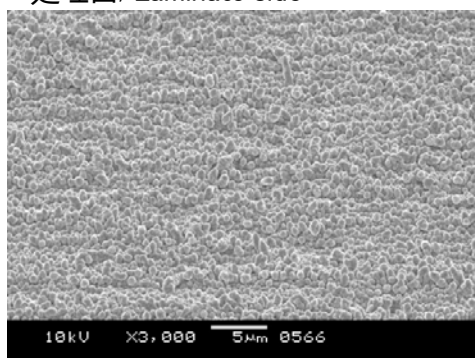
- ・ 日本/Japan

代表性特性数据/Representative date

	μm	Area weight (g/m^2)	Laminate side $R_z(\mu\text{m})$	Tensile Strength (N/mm^2)	Elongation (%)	Peel Strength (kg/cm)@FR-4
3EC-M1S-VLP	7	64	1.8	500	4	0.7

※上述表列为代表性数据非保证值
This is representative data, not guaranteed.

处理面/Laminate side



阻剂面/ resist side

